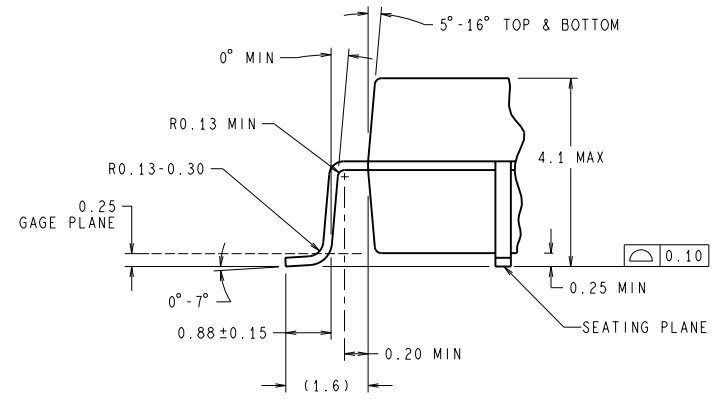
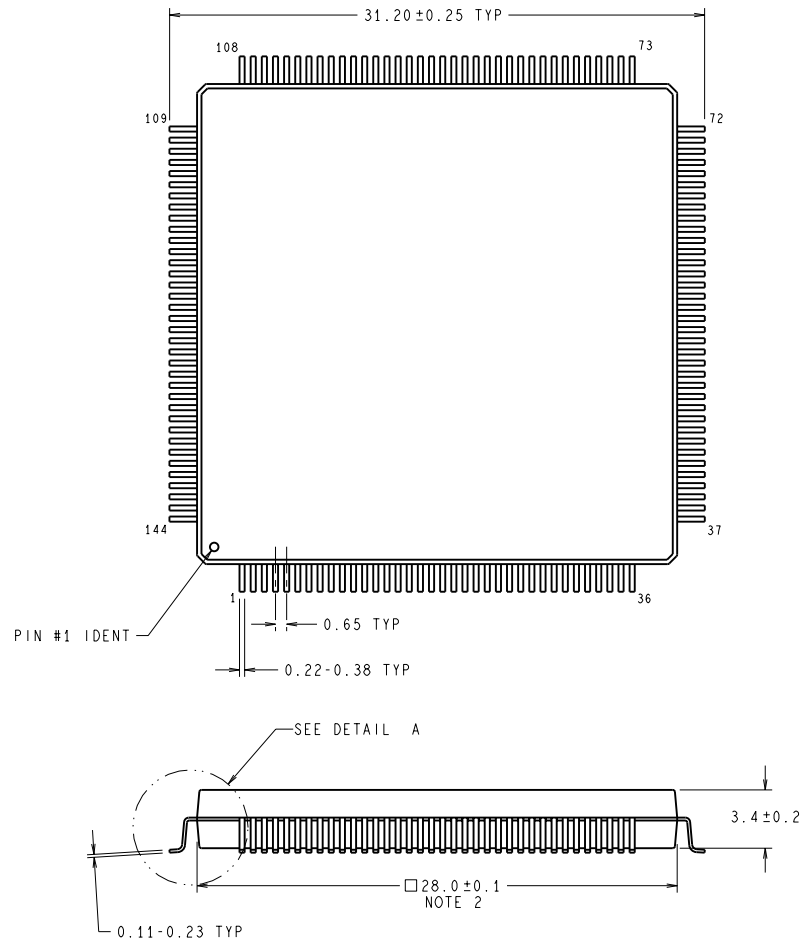


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
C	REVISE AND REDRAW PER JEDEC MS-022.	11039	07/13/95	DEG/



DETAIL A  
TYP, SCALE: 15X

DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH:  
7.62 MICROMETERS MINIMUM SOLDER PLATING (85/15)  
THICKNESS ON COPPER.
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.  
MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.
- REFERENCE JEDEC STANDARD MS-022, VARIATION DC-1,  
DATED FEB/95.

APPROVALS	DATE	 National Semiconductor 2900 Semiconductor dr., Santa Clara, CA 95052-8090			
DRAWN	D. E. Grady 07/13/95				
DFTG. CHK.			PQFP, JEDEC METRIC, (S), 28 X 28 X 3.4mm, 144 LEAD		
ENGR. CHK.					
 PROJECTION INCH (MM)		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	MKT-VUY144A	C
DO NOT SCALE DRAWING				SHEET 1 of 1	